

Notice of References Cited	Application/Control No. 10/825,103	Applicant(s)/Patent Under Reexamination SAITO ET AL.	
	Examiner Craig A. Renner	Art Unit 2627	Page 1 of 1

U.S. PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
	A	US-			
	B	US-			
	C	US-			
	D	US-			
	E	US-			
	F	US-			
	G	US-			
	H	US-			
	I	US-			
	J	US-			
	K	US-			
	L	US-			
	M	US-			

FOREIGN PATENT DOCUMENTS

*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Country	Name	Classification
	N					
	O					
	P					
	Q					
	R					
	S					
	T					

NON-PATENT DOCUMENTS

*		Include as applicable: Author, Title Date, Publisher, Edition or Volume, Pertinent Pages)
	U	"Mechanical Packaging Scheme With Considerations for Maximum ESD/EMC Protection, Efficient Cooling And Quiet Office Environment," IBM Technical Disclosure Bulletin, Vol. 33, Iss. 9, Pages 379-383, February 1, 1991.
	V	Machine Translation of JP 2001-125667, published May 11, 2001 to Fujihata et al.
	W	
	X	

*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.